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March 2013

FQT7N10

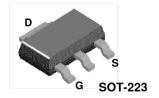
N-Channel QFET® MOSFET 100 V, 1.7 A, 350 m Ω

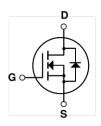
Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor®'s proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

Features

- 1.7 A, 100 V, $R_{DS(on)}$ =350 m $\Omega(Max.)$ @ V_{GS} =10 V, I_D =0.85 A
- Low Gate Charge (Typ. 5.8 nC)
- Low Crss (Typ. 10 pF)
- 100% Avalanche Tested





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQT7N10	Unit
V _{DSS}	Drain-Source Voltage		100	V
I _D	Drain Current - Continuous (T _C = 25°C) - Continuous (T _C = 70°C)		1.7	А
			1.36	А
I _{DM}	Drain Current - Pulsed	(Note 1)	6.8	А
V _{GSS}	Gate-Source Voltage		±25	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	50	mJ
I _{AR}	Avalanche Current	(Note 1)	1.7	А
E _{AR}	Repetitive Avalanche Energy	(Note 1)	0.2	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	6.0	V/ns
P _D	Power Dissipation (T _C = 25°C)		2.0	W
	- Derate above 25°C		0.016	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

Thermal Characteristics

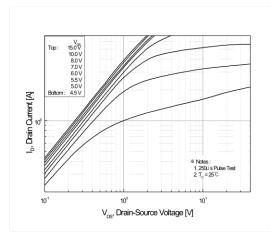
Symbol	Parameter	Тур	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		62.5	°C/W

^{*} When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions	i	Min	Тур	Max	Unit
Off Cha	racteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		100			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced	to 25°C		0.1		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 100 V, V _{GS} = 0 V				1	μΑ
		V _{DS} = 80 V, T _C = 125°C				10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 25 V, V _{DS} = 0 V				100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -25 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
On Cha	racteristics						
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 0.85 A			0.28	0.35	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 0.85 A	(Note 4)		1.85		S
Dynam C _{iss} C _{oss}	ic Characteristics Input Capacitance Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz			190 60	250 75	pF pF
C _{rss}	Reverse Transfer Capacitance				10	13	pF
Switchi	ng Characteristics						
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 50 \text{ V}, I_D = 7.3 \text{ A},$ $R_G = 25 \Omega$			7	25	ns
t _r	Turn-On Rise Time				24	60	ns
t _{d(off)}	Turn-Off Delay Time				13	35	ns
t _f	Turn-Off Fall Time		(Note 4, 5)		19	50	ns
Qg	Total Gate Charge	V _{DS} = 80 V, I _D = 7.3 A,			5.8	7.5	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V (Note 4, 5)			1.4		nC
Q _{gd}	Gate-Drain Charge				2.5		nC
Drain-S	Source Diode Characteristics at Maximum Continuous Drain-Source Dio		S			1.7	А
I _{SM}	Maximum Pulsed Drain-Source Diode F	orward Current				6.8	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 1.7 A				1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 7.3 A,			70		ns
Q _{rr}	Reverse Recovery Charge	dl _E / dt = 100 A/μs	(Note 4)		150		nC

- Notes: 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 26mH, I_{AS} = 1.7A, V_{DD} = 25V, R_{G} = 25 Ω , Starting T_{J} = 25°C 3. $I_{SD} \le 7.3A$, di/dt $\le 300A/\mu s$, $V_{DD} \le BV_{DSS}$, Starting T_{J} = 25°C 4. Pulse Test : Pulse width $\le 300\mu s$, Duty cycle $\le 2\%$ 5. Essentially independent of operating temperature

Typical Characteristics



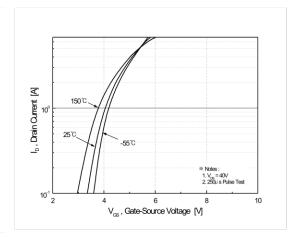


Figure 1. On-Region Characteristics

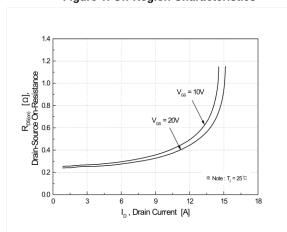


Figure 2. Transfer Characteristics

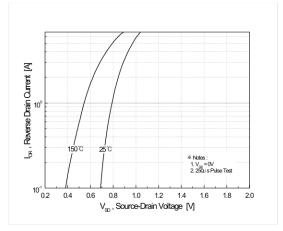


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

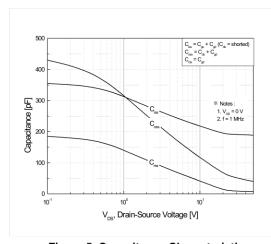


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

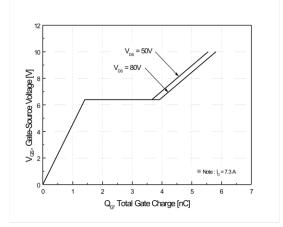
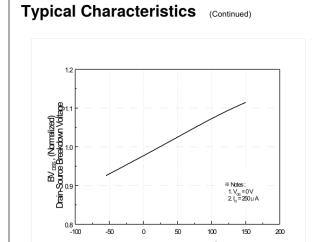


Figure 5. Capacitance Characteristics

Figure 6. Gate Charge Characteristics



-50

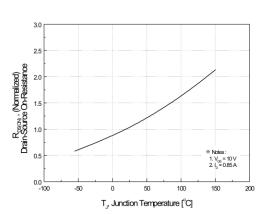


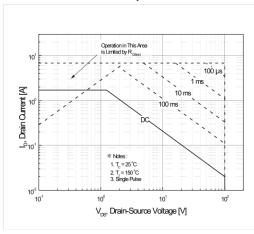
Figure 7. Breakdown Voltage Variation vs. Temperature

T_., Junction Temperature [°C]

150

200

Figure 8. On-Resistance Variation vs. Temperature



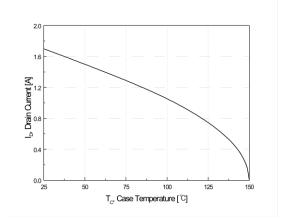


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

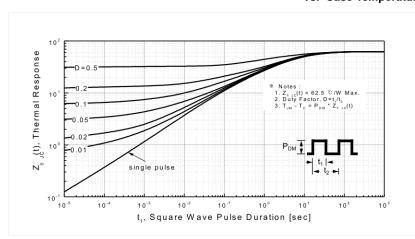
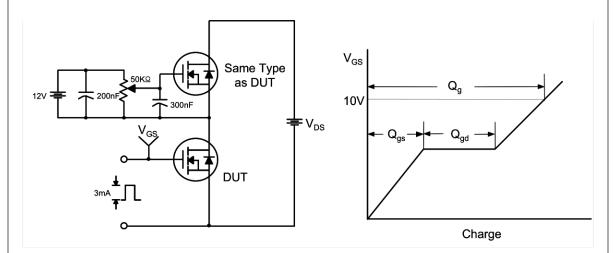
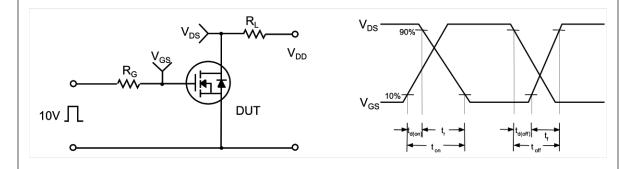


Figure 11. Transient Thermal Response Curve

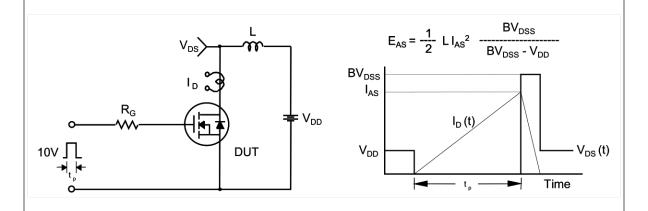
Gate Charge Test Circuit & Waveform



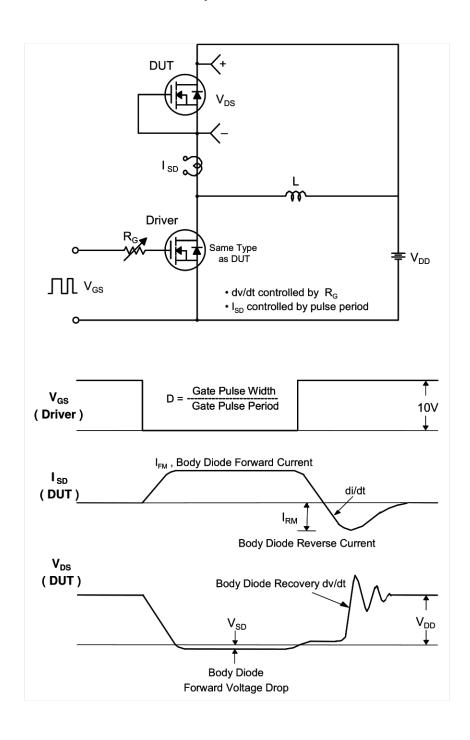
Resistive Switching Test Circuit & Waveforms

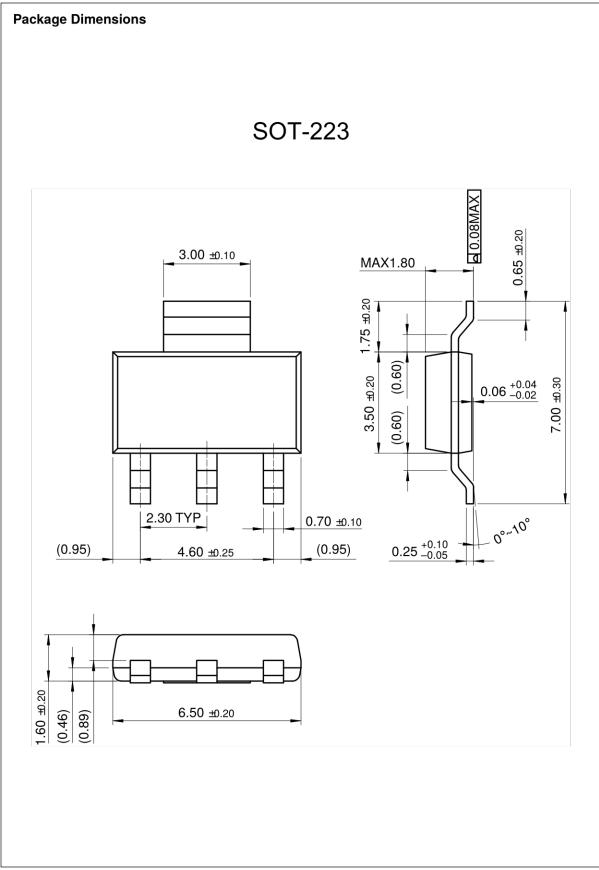


Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms









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